



7 + T 3 PR W] € F , G S \$ @ P T 1 p À 3 + U À P T À S S P S 3 3 S 6 R F

Isolation Voltage	V_{iso}	3750	Vrms
Operating Temperature	T_{opr}	-55~110	
Junction Temperature	T_j	125	
Storage Temperature	T_{stg}	-55~125	
Soldering Temperature	T_{sol}	260	
Peak pulse voltage ($T_j=25$; non-repetitive,off-state)	V_{pp}	1	kV

: μ
:

(Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit	
Input	Forward Voltage	V_F	$I_F=10mA$	-	1.2	1.5	V	
	Reverse Current	I_R	$V_R=6V$	-	-	1	μA	
	Input Capacitance	C_{in}	$V=0, f=1kHz$	-	14	-	pF	
Output	Peak Off-state Current, Either Direction	I_{OFF}	$V_{OFF}=Rated V_{OFF}$ $I_F=0$	-	-	100	nA	
	Peak On-state Voltage, Either Direction	V_{TM}	$I_{TM}=100mA$	-	2	2.5	V	
	Critical Rate of Rise of Off-state voltage	dV/dt	$V_{PEAK}=Rated V_{PEAK}$ $I_F=0$	2000	-	-	V/ μs	
Transfer Characteristics	LED Trigger Current	JOCSR21A JOCSR31A	I_{FT}	Terminal Voltage=3V $I_{TM}=100mA$	-	-	10	mA
		JOCSR21B JOCSR31B			-	-	5	
		JOCSR21C JOCSR31C			-	-	3	
	Holding Current	I_H	$I_{TM}=2mA,$ $I_F=Rated I_{FT}$	-	500	-	μA	
	Isolation Resistance	R_{ISO}	DC500V 40~60%R.H.	10^{12}	10^{14}	-		
	Floating Capacitance	C_{IO}	$V=0,$ $f=1MHz$	-	5	-	pF	
	Response Time	t_{on}	$V_D=6V,$ $R_L=100$, $I_F=20mA$	-	15	50	μs	

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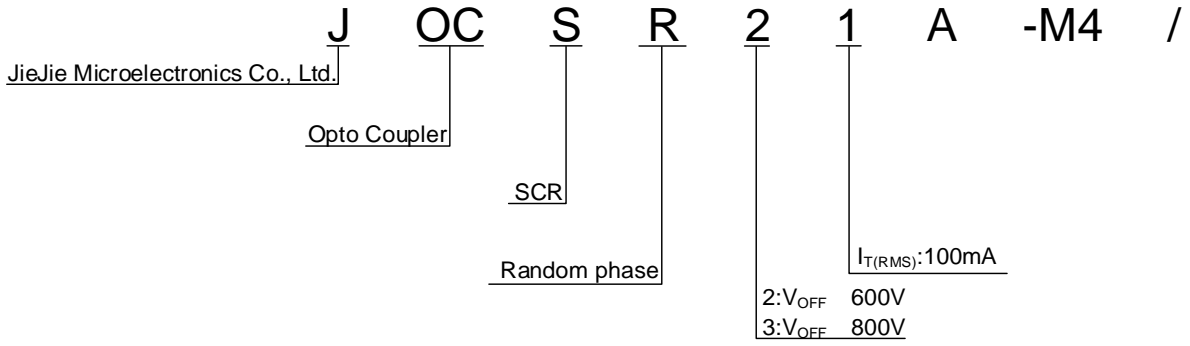


FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

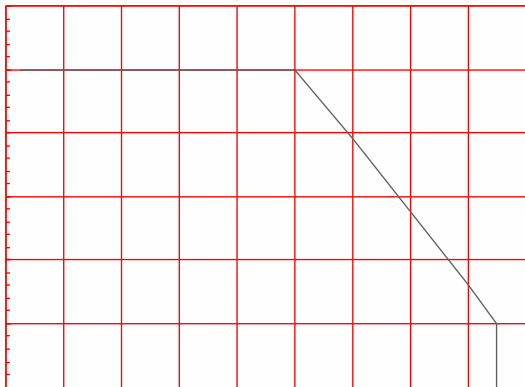


FIG.2: On-state Terminal Current vs. Ambient Temperature

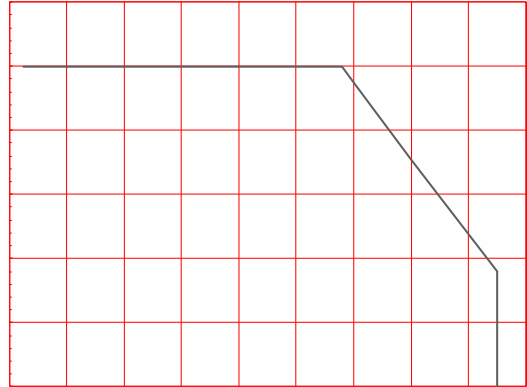


FIG.3: Forward Current vs. Forward Voltage

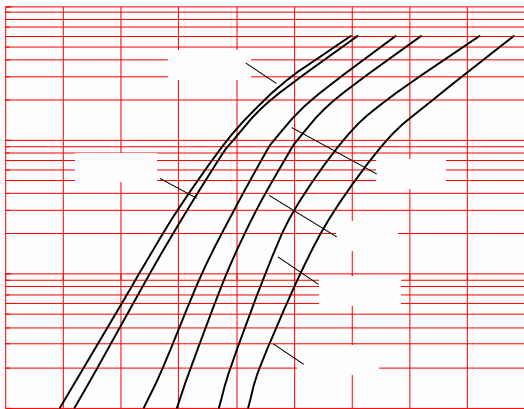


FIG.4: Normalized Off-state Terminal Current vs. Ambient Temperature

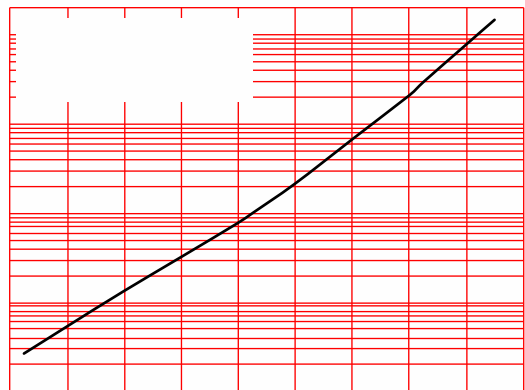


FIG.5: Normalized Off-state Terminal Voltage vs. Ambient Temperature



FIG.6: Normalized Trigger Current vs. Ambient Temperature



FIG.12: Test Circuits of Turn On Time

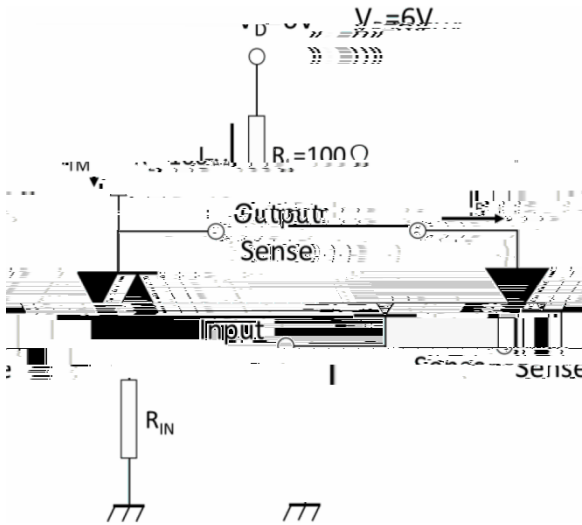


FIG.13: Waveforms of Turn On Time

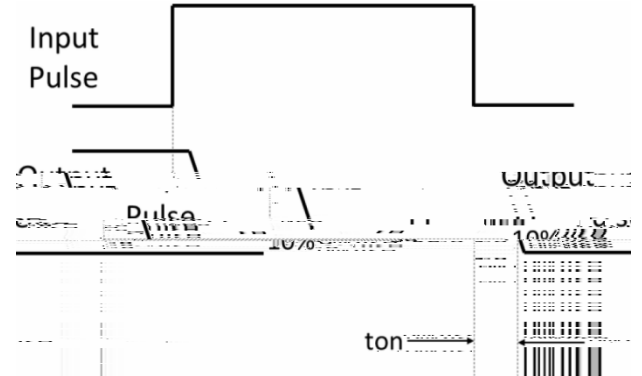


Fig.14: Test Circuits of dV/dt

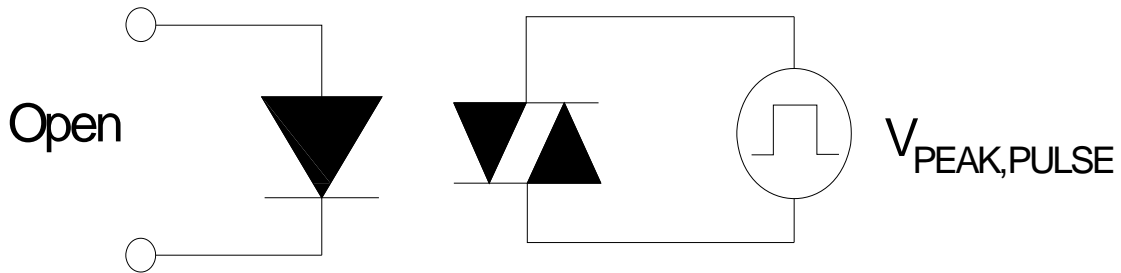


Fig.15: Waveforms of dV/dt

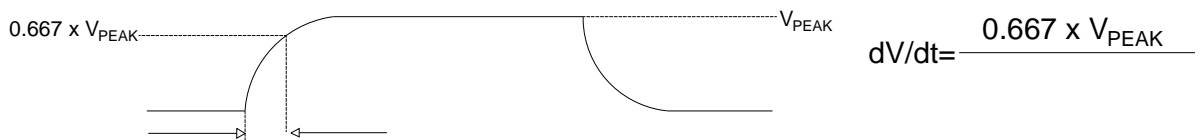
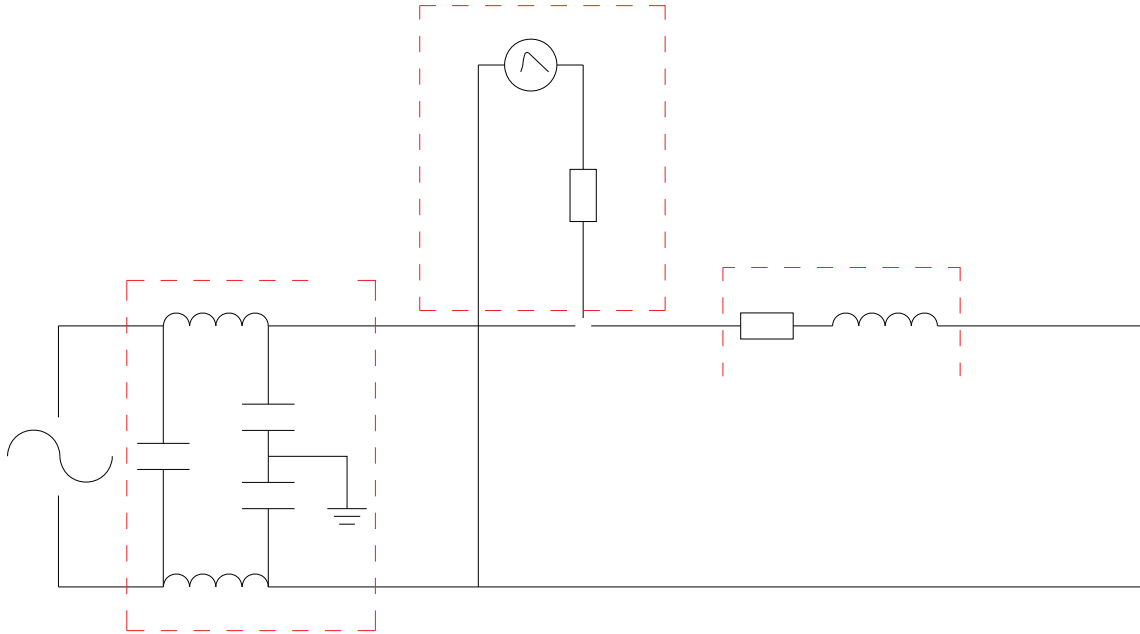
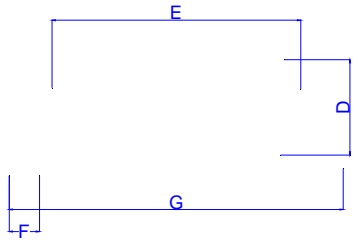
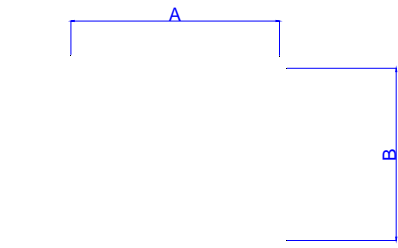


FIG.16: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards





Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.80	0.173		0.189
B	3.60		4.20	0.142		0.165
C						
E						
G	6.70			0.264C	i	4
I						

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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